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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

the Application of:

LLOYD L. POLLARD, II, ET AL.

Application No.: 09/471,220

Filed: December 23, 1999

For: **Dynamic Thermal Management For
Integrated Circuits**

Art Group: 2123

Examiner: Jones, Hugh M.

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TRANSMITTAL OF FORMAL DRAWINGS

Sir:

Enclosed herewith for filing in the above-identified U.S. Patent Application are the formal drawings, 3 sheets including 3 Figures. Please charge any additional fees or credit any overpayment to Deposit Account No. 02-2666. A duplicate copy of the Fee Transmittal is enclosed for this purpose.

Respectfully submitted,

Blakely, Sokoloff, Taylor & Zafman LLP

Dated: March 5, 2004

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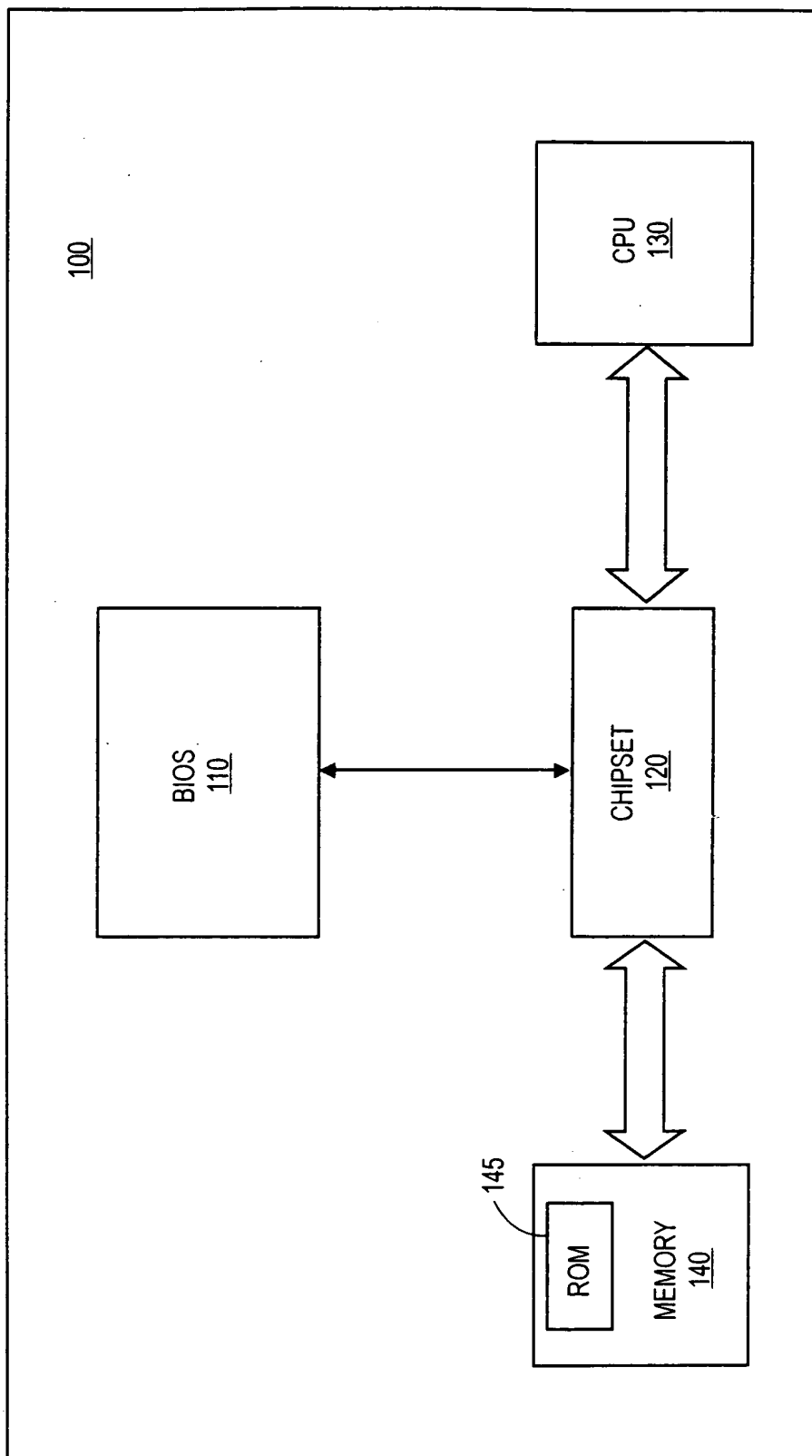
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FIG. 1



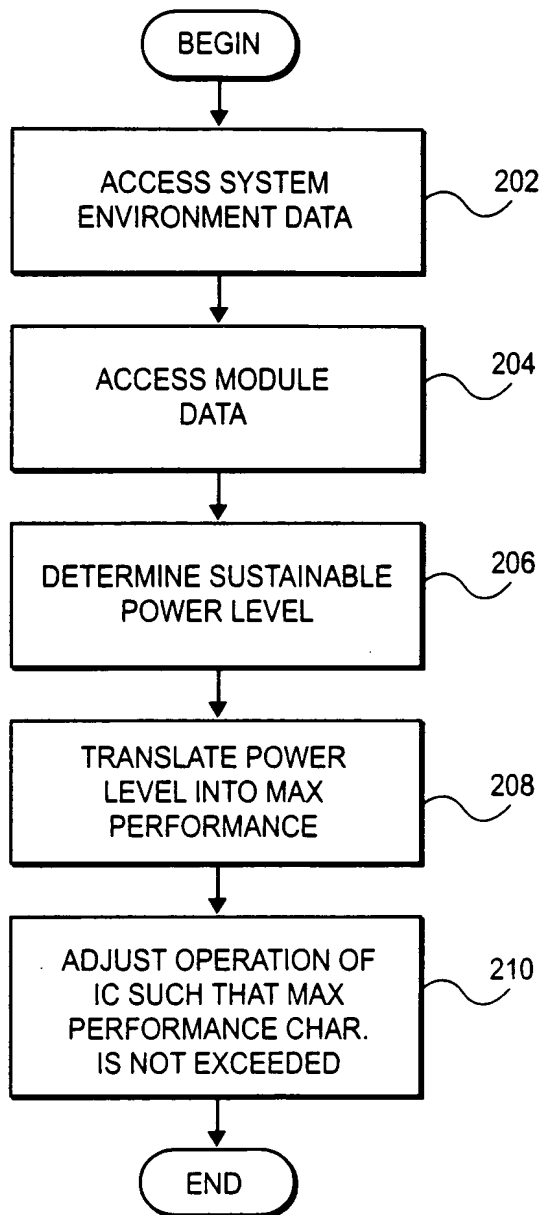
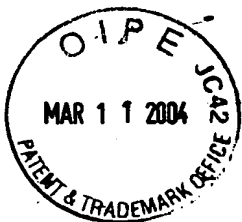


FIG. 2

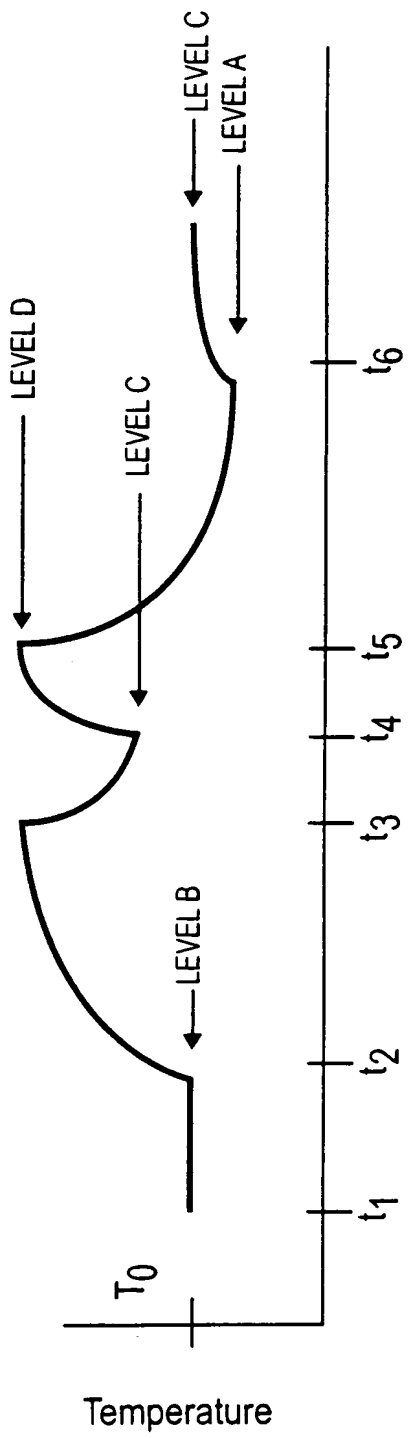
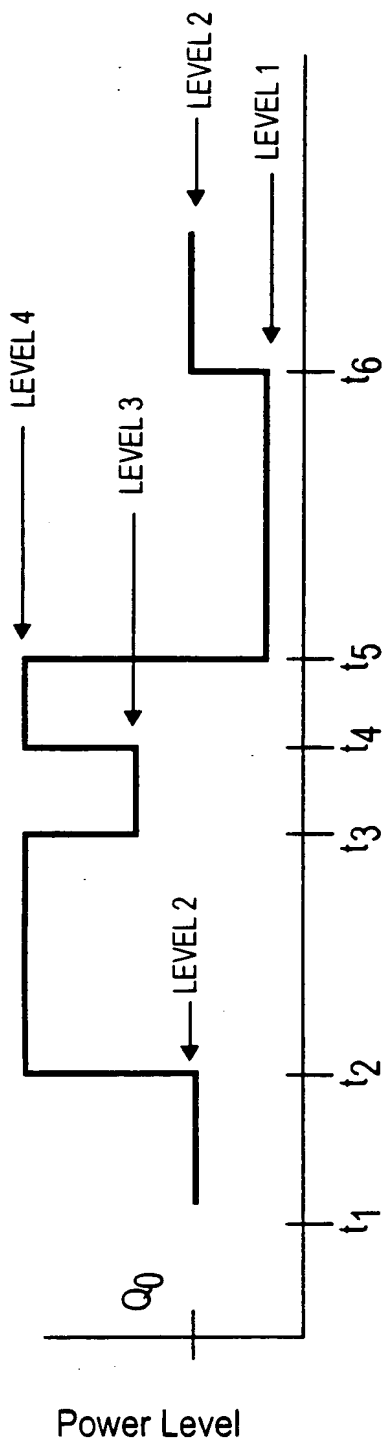


FIG. 3
(PRIOR ART)